

IN THE CLAIMS:

The status of each claim that has been introduced in the above-referenced application is identified in the ensuing listing of the claims. This listing of the claims replaces all previously submitted claims listings.

1. (Currently amended) A method of labeling a semiconductor device component, comprising:
~~providing at least one substrate;~~
~~disposing at least one layer of an unconsolidated material over a surface of said~~the ~~at least one substrate; and~~
at least partially consolidating unconsolidated material over a surface of at least one substrate a plurality of selected areas of said~~the~~ ~~at least one layer in a sequential fashion to form a corresponding layer at least a portion of~~ a mark over ~~said~~the surface.
2. (Currently amended) The method of claim ~~1~~23, wherein ~~said~~ disposing comprises disposing at least one layer of an uncured polymer.
3. (Currently amended) The method of claim 2, wherein ~~said~~ at least partially consolidating comprises at least partially curing polymer at ~~said~~the plurality of selected areas.
4. (Currently amended) The method of claim 2, wherein ~~said~~ disposing comprises disposing at least one layer of an uncured photopolymer.
5. (Currently amended) The method of claim 4, wherein ~~said~~ at least partially consolidating comprises at least partially curing photopolymer at ~~said~~the plurality of selected areas.

6. (Currently amended) The method of claim 5, wherein ~~said~~ at least partially curing comprises directing a UV laser over ~~said~~the plurality of selected areas of ~~said~~the at least one layer.

7. (Currently amended) The method of claim 6, wherein ~~said~~ at least partially curing comprises curing at least edges of ~~said~~the corresponding layer of ~~said~~the mark.

8. (Currently amended) The method of claim 7, further comprising further curing uncured photopolymer bounded by ~~said~~the edges.

9. (Currently amended) The method of claim 8, wherein ~~said~~ further curing comprises thermally curing ~~said~~the uncured photopolymer.

10. (Currently amended) The method of claim 8, wherein ~~said~~ further curing comprises subjecting ~~said~~the uncured photopolymer to UV radiation.

11. (Currently amended) The method of claim 7, wherein ~~said~~ curing at least edges comprises curing at least an outer periphery of ~~said~~the mark.

12. (Currently amended) The method of claim 11, wherein ~~said~~ curing at least edges further comprises curing an inner periphery of ~~said~~the mark.

13. (Currently amended) The method of claim ~~12~~6, wherein ~~said at least partially~~ sequentially consolidating comprises sequentially consolidating a plurality of superimposed, contiguous layers of unconsolidated material and securing adjacent ones of ~~said~~the plurality of layers to one another.

14. (Currently amended) A method of labeling a semiconductor device component, comprising:

placing at least one substrate in a horizontal plane; and
~~stereolithographically fabricating~~selectively consolidating material to form at least one mark on
~~said~~the at least one substrate.

15. (Currently amended) The method of claim 14, wherein ~~said stereolithographically fabricating~~selectively consolidating comprises:
disposing a layer comprising unconsolidated material on ~~said~~the at least one substrate; and
at least partially consolidating unconsolidated material in a plurality of selected regions of
~~said~~the layer in a sequential fashion.

16. (Currently amended) The method of claim 15, wherein ~~said stereolithographically fabricating~~selectively consolidating further comprises:
repeating ~~said~~the disposing and ~~said~~the at least partially consolidating at least once.

17. (Currently amended) The method of claim 14, further comprising:
recognizing a location and an orientation of ~~said~~the at least one substrate.

18. (Currently amended) The method of claim 17, further comprising storing data
including at least one physical parameter of ~~said~~the at least one substrate and of ~~said~~the at least
one mark in computer memory and using ~~said~~the stored data in conjunction with a machine
vision system to recognize ~~said~~the location and ~~said~~the orientation of ~~said~~the at least one
substrate.

19. (Currently amended) The method of claim 18, further ~~including~~comprising
storing in computer memory at least one parameter of another structure to be associated with
~~said~~the at least one substrate.

20. (Currently amended) The method of claim 18, further comprising using ~~said~~the
stored data, in conjunction with ~~said~~the machine vision system, to effect ~~said~~

~~stereolithographically fabricating said~~selectively consolidating material to form the at least one mark.

21. (Currently amended) The method of claim 17, further comprising recognizing ~~said~~the location of ~~said~~the at least one substrate on which ~~said~~the at least one mark is to be fabricated.

22. (Currently amended) The method of claim 17, further ~~including comprising~~ securing ~~said~~the at least one substrate to a carrier prior to ~~said~~ placing ~~said~~the at least one substrate in ~~said~~the horizontal plane.

23. (New) The method of claim 1, further comprising:
disposing at least one layer of the unconsolidated material over the surface of the at least one substrate.

24. (New) The method of claim 23, wherein at least partially consolidating comprises at least partially consolidating the unconsolidated material at a plurality of selected areas of the at least one layer to form a corresponding layer of the mark.

25. (New) The method of claim 1, wherein at least partially consolidating is effected under control of a program.

26. (New) The method of claim 1, wherein at least partially consolidating comprises forming a plurality of adjacent, mutually adhered regions of the mark.